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MS5561C

Micro Altimeter

SPECIFICATIONS

- 10 - 1100 mbar / 1 – 110 kPa absolute pressure range
- High accuracy temperature measurement
- Integrated miniature pressure sensor 4.75 x 4.25 mm
- Thin design of 1.6 mm
- Piezoresistive silicon micromachined sensor
- 6 coefficients for software compensation stored on-chip
- 16 Bit ADC, sigma delta converter
- 3-wire serial interface
- 1 system clock line (32.768 kHz)
- Low voltage and low power consumption

The MS5561C is a SMD-hybrid device including a precision piezo-resistive pressure sensor and an ADC-Interface IC. It uses a three-wire serial interface for communication. The module dimensions of 4.75 mm x 4.25 mm and a height of only 1.6 mm allows for up-to-date SMD design. It provides a 16 bit data word from a pressure and temperature dependent voltage. The MS5561C is a low power, low voltage device with automatic power down (ON/OFF) switching. A 3-wire interface is used for all communications with a micro-controller.

FEATURES

- Pressure resolution 0.1 mbar
- Operating temperature -40°C to +85°C
- Supply voltage 2.2 V to 3.6 V
- Low supply current, typ. 4 μ A
- Standby current < 0.1 μ A
- Calibrated temperature and pressure sensor for 2nd order compensation
- ESD protected, HBM 4 kV

APPLICATIONS

- Mobile phones
- GPS receivers
- Altimeter applications
- Personal Navigation Devices (PND)
- Digital cameras with altimeter function

BLOCK DIAGRAM

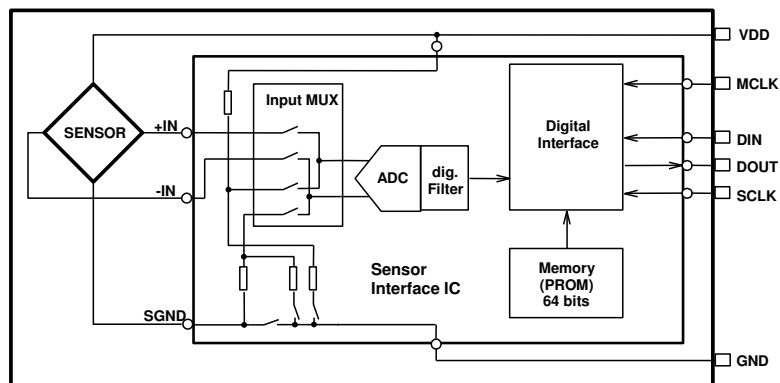


Fig. 1: Block diagram MS5561C

PIN CONFIGURATION

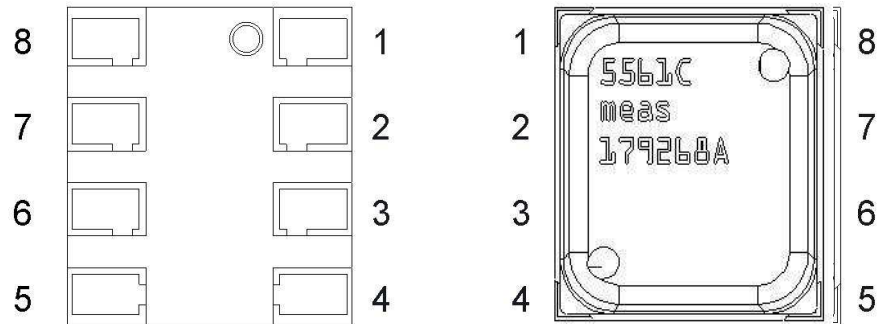


Fig. 2: Pin configuration of MS5561C

Pin Name	Pin	Type	Function
SCLK	1	I	Serial data clock
GND	2	G	Ground
PV (1)	3	N	Negative programming voltage
PEN (1)	4	I	Programming enable
VDD	5	P	Positive supply voltage
MCLK	6	I	Master clock (32.768 kHz)
DIN	7	I	Serial data input
DOUT	8	O	Serial data output

NOTE

- Pin 3 (PV) and Pin 4 (PEN) are only used by the manufacturer for calibration purposes and should not be connected.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Min	Max	Unit	Notes
Supply voltage	V _{DD}	T _a = 25 °C	-0.3	4	V	
Storage temperature	T _s		-40	+85	°C	1
Overpressure	P	T _a = 25 °C		5	bar	

NOTE

- Storage and operation in an environment of dry and non-corrosive gases.

RECOMMENDED OPERATING CONDITIONS

(Ta = 25 °C, V_{DD} = 3.0 V unless noted otherwise)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Operating pressure range	p		10		1100	mbar abs.
Supply voltage	V _{DD}		2.2	3.0	3.6	V
Supply current, average (1) during conversion (2) standby (no conversion)	I _{avg} I _{sc} I _{ss}	V _{DD} = 3.0 V		4 1	0.1	μA mA μA
Current consumption into MCLK (3)		MCLK = 32.768 kHz			0.5	μA
Operating temperature range	T		-40	+25	+85	°C
Conversion time	t _{conv}	MCLK = 32.768 kHz			35	ms
External clock signal (4)	MCLK		30.000	32.768	35.000	kHz
Duty cycle of MCLK			40/60	50/50	60/40	%
Serial data clock	SCLK				500	kHz

NOTES

- 1) Under the assumption of one conversion every second. Conversion means either a pressure or a temperature measurement started by a command to the serial interface of MS5561C.
- 2) During conversion the sensor will be switched on and off in order to reduce power consumption; the total on time within a conversion is about 2 ms.
- 3) This value can be reduced by switching off MCLK while MS5561C is in standby mode.
- 4) It is strongly recommended that a crystal oscillator be used because the device is sensitive to clock jitter. A square-wave form of the clock signal is a must.

ELECTRICAL CHARACTERISTICS

DIGITAL INPUTS

(T = -40 °C .. 85 °C, V_{DD} = 2.2 V .. 3.6 V)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Input High Voltage	V _{IH}		80% V _{DD}		100% V _{DD}	V
Input Low Voltage	V _{IL}		0% V _{DD}		20% V _{DD}	V
Signal Rise Time	t _r			200		ns
Signal Fall Time	t _f			200		ns

DIGITAL OUTPUTS

(T = -40 °C .. 85 °C V_{DD} = 2.2 V .. 3.6 V)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output High Voltage	V _{OH}	I _{source} = 0.6 mA	80% V _{DD}		100% V _{DD}	V
Output Low Voltage	V _{OL}	I _{sink} = 0.6 mA	0% V _{DD}		20% V _{DD}	V
Signal Rise Time	t _r			200		ns
Signal Fall Time	t _f			200		ns

AD-CONVERTER

(T = -40 °C .. 85 °C V_{DD} = 2.2 V .. 3.6 V)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Resolution				16		Bit
Linear Range			4'000		40'000	LSB
Conversion Time		MCLK = 32.768 kHz			35	ms
INL		Within linear range	-5		+5	LSB

PRESSURE OUTPUT CHARACTERISTICS

With the calibration data stored in the interface IC of the MS5561C, the following characteristics can be achieved:
($V_{DD} = 3.0\text{ V}$ unless noted otherwise)

Parameter	Conditions	Min	Typ	Max	Unit	Notes
Resolution	$p = 300 \dots 1000\text{ mbar}$ $T_a = 25^\circ\text{C}$		0.1		mbar	1
Absolute Pressure Accuracy	$p = 750 \dots 1100\text{ mbar}$ $T_a = 25^\circ\text{C}$	-1.5		+1.5	mbar	2
Relative Pressure Accuracy	$p = 750 \dots 1100\text{ mbar}$ $T_a = 25^\circ\text{C}$	-0.5		+0.5	mbar	3
Relative Pressure Error over Temperature	$T = 0 \dots +50^\circ\text{C}$ $p = 300 \dots 1000\text{ mbar}$	-1		+1	mbar	4
	$T = -40 \dots +85^\circ\text{C}$ $p = 300 \dots 1000\text{ mbar}$	-2		+7	mbar	4
Long-term Stability	12 months		-1		mbar	5
Maximum Error over Supply Voltage	$V_{DD} = 2.2 \dots 3.6\text{ V}$ $p = \text{const.}$	-1.6		1.6	mbar	

NOTES

- 1) A stable pressure reading of the given resolution requires taking the average of 2 to 4 subsequent pressure values due to noise of the ADC.
- 2) Maximum error of pressure reading over the pressure range.
- 3) Maximum error of pressure reading over the pressure range after offset adjustment at one pressure point.
- 4) With the second-order temperature compensation as described in Section "FUNCTION". See next section for typical operating curves.
- 5) The long-term stability is measured with non-soldered devices.

TEMPERATURE OUTPUT CHARACTERISTICS

This temperature information is not required for most applications, but it is necessary to allow for temperature compensation of the output.

($V_{DD} = 3.0\text{ V}$ unless noted otherwise)

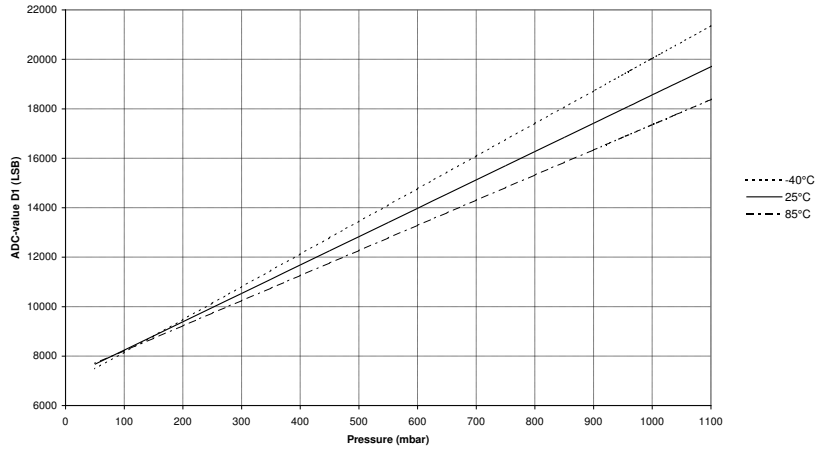
Parameter	Conditions	Min	Typ	Max	Unit	Notes
Resolution		0.005	0.01	0.015	$^\circ\text{C}$	
Accuracy	$T = 20\text{ }^\circ\text{C}$	-0.8		0.8	$^\circ\text{C}$	
	$T = -40 \dots + 85^\circ\text{C}$	-2		+3	$^\circ\text{C}$	1
Maximum Error over Supply Voltage	$V_{DD} = 2.2 \dots 3.6\text{ V}$	-0.2		+0.2	$^\circ\text{C}$	2

NOTES

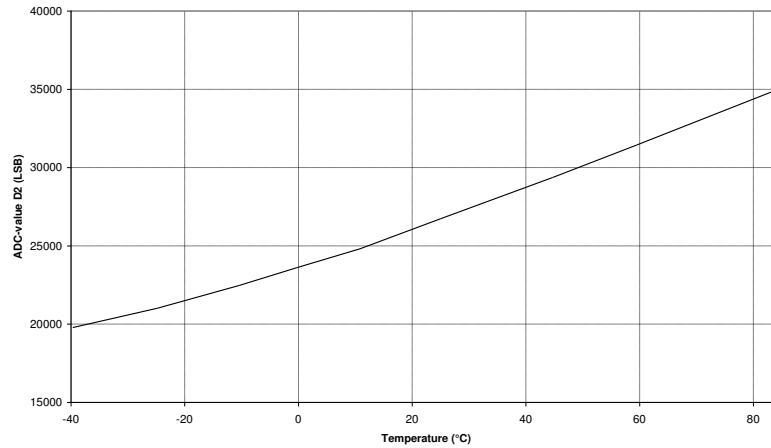
- 1) With the second-order temperature compensation as described in Section "FUNCTION". See next section for typical operating curves.
- 2) At $T_a = 25\text{ }^\circ\text{C}$.

TYPICAL PERFORMANCE CURVES

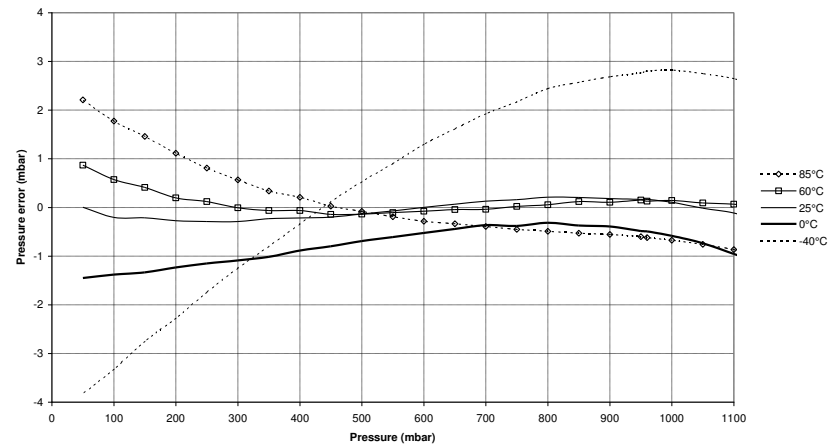
ADC-value D1 vs Pressure (typical)



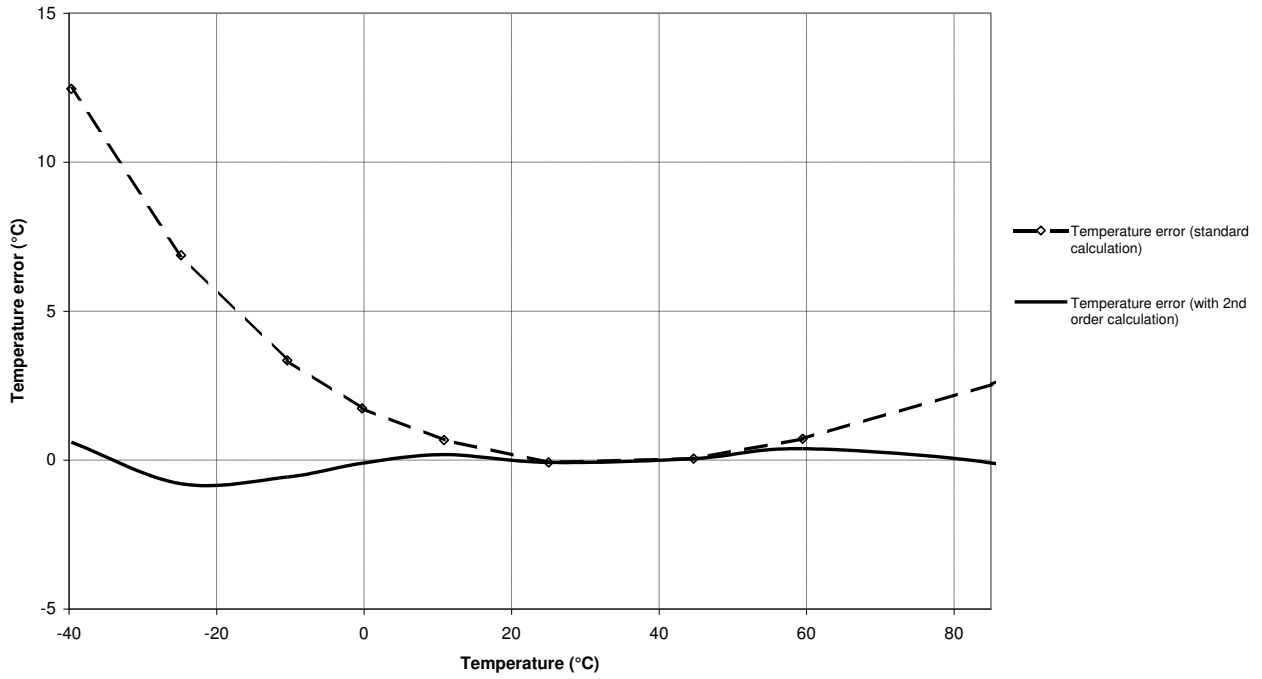
ADC-value D2 vs Temperature (typical)



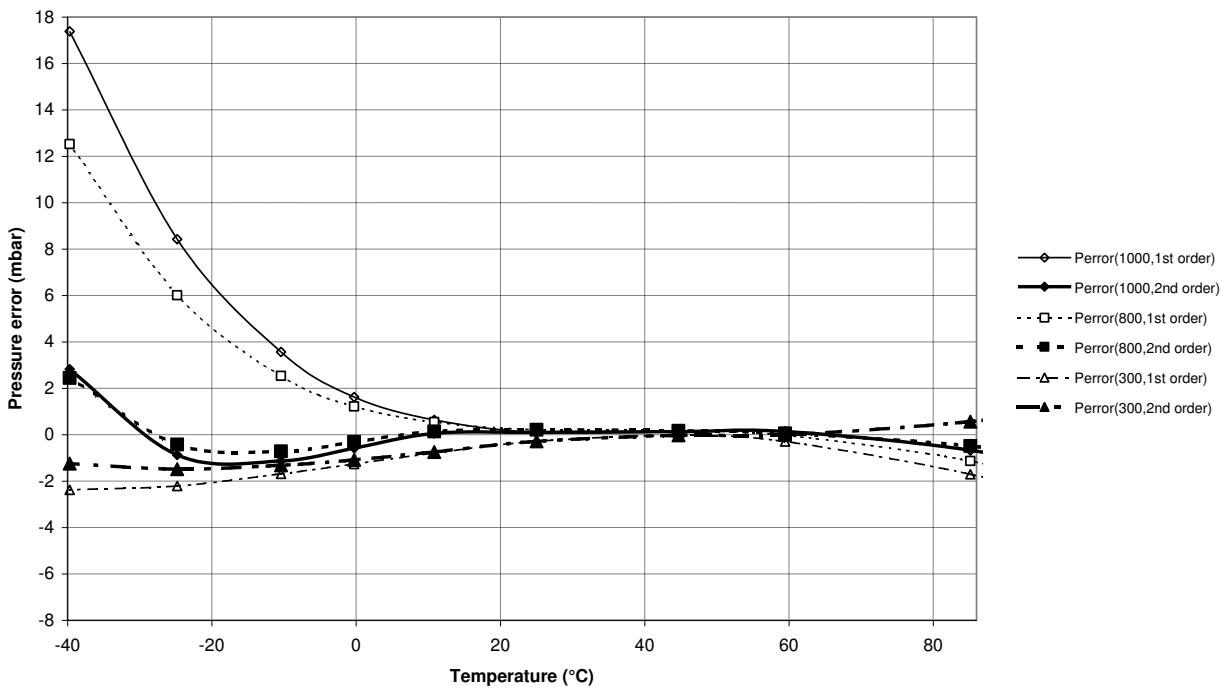
Absolute Pressure Accuracy after Calibration, 2nd order compensation



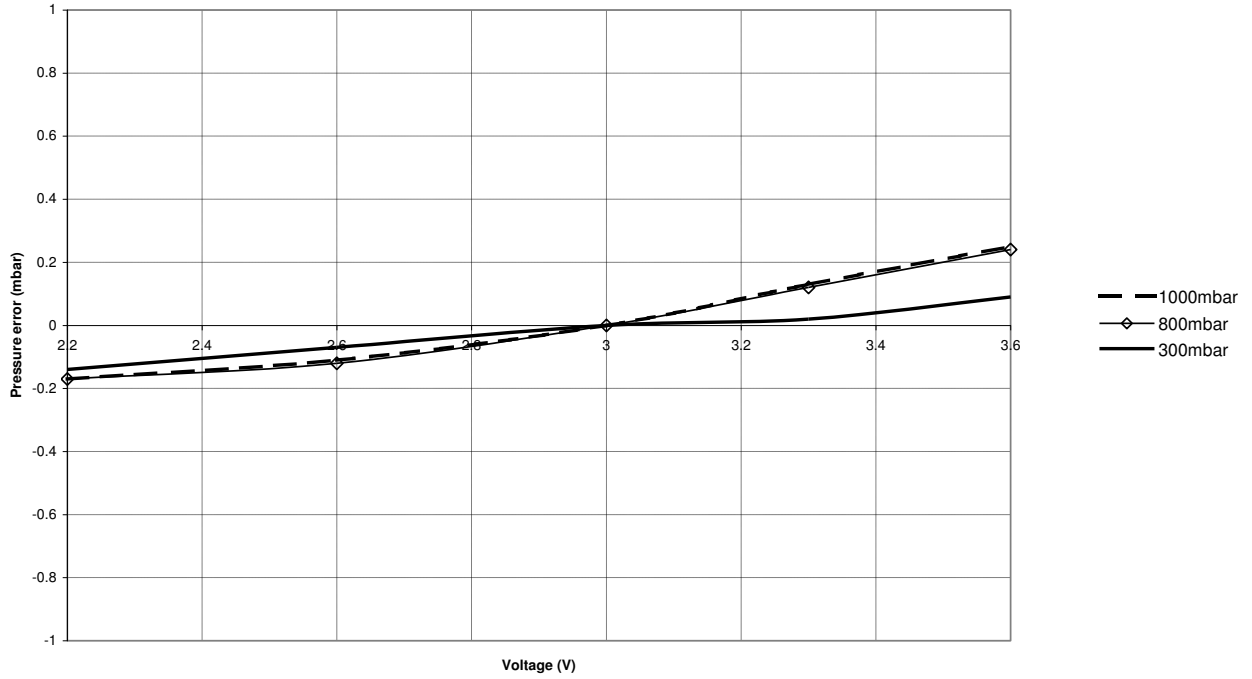
Temperature Error Accuracy vs temperature (typical)



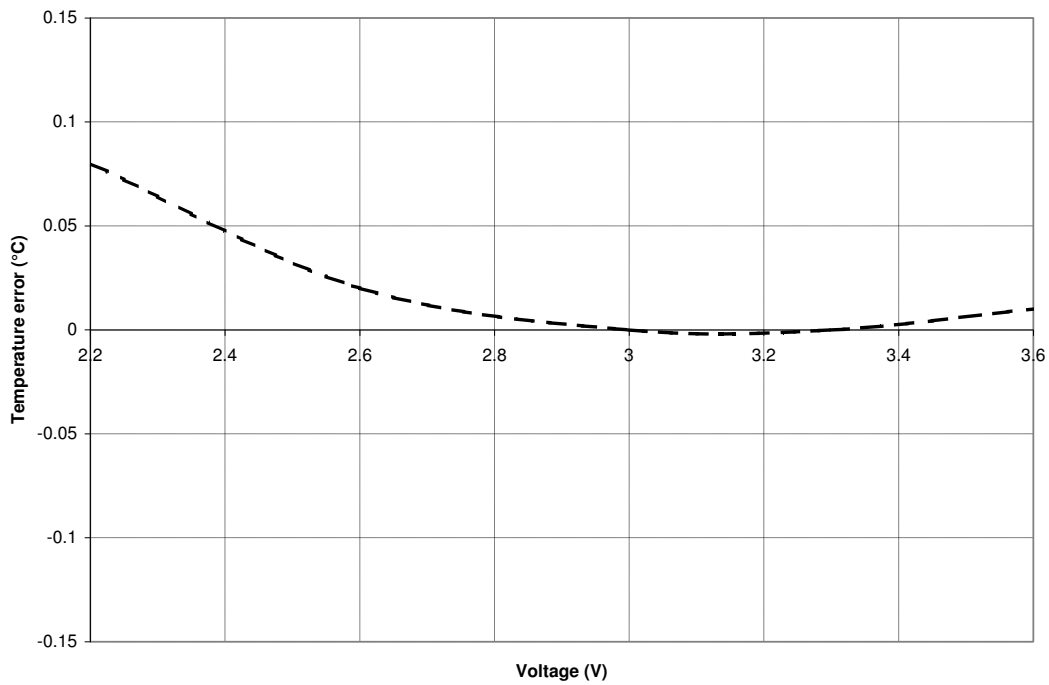
Pressure Error Accuracy vs temperature (typical)



Pressure error vs supply voltage (typical)



Temperature error vs supply voltage (typical)



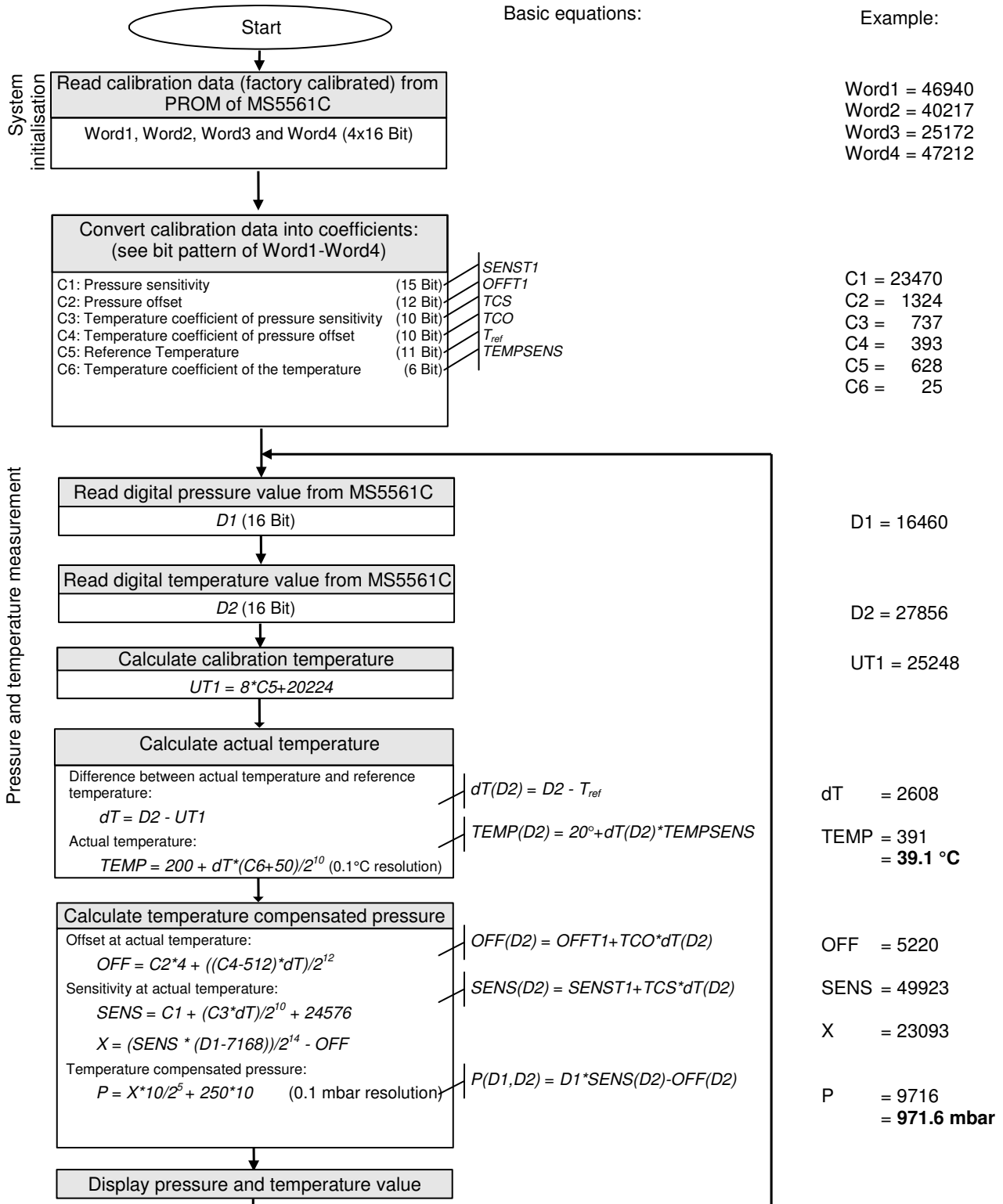


Fig. 3: Flow chart for pressure and temperature reading and software compensation

NOTES

- 1) Readings of D2 can be done less frequently, but the display will be less stable in this case.
- 2) For a stable display of 1 mbar resolution, it is recommended to display the average of 8 subsequent pressure values.

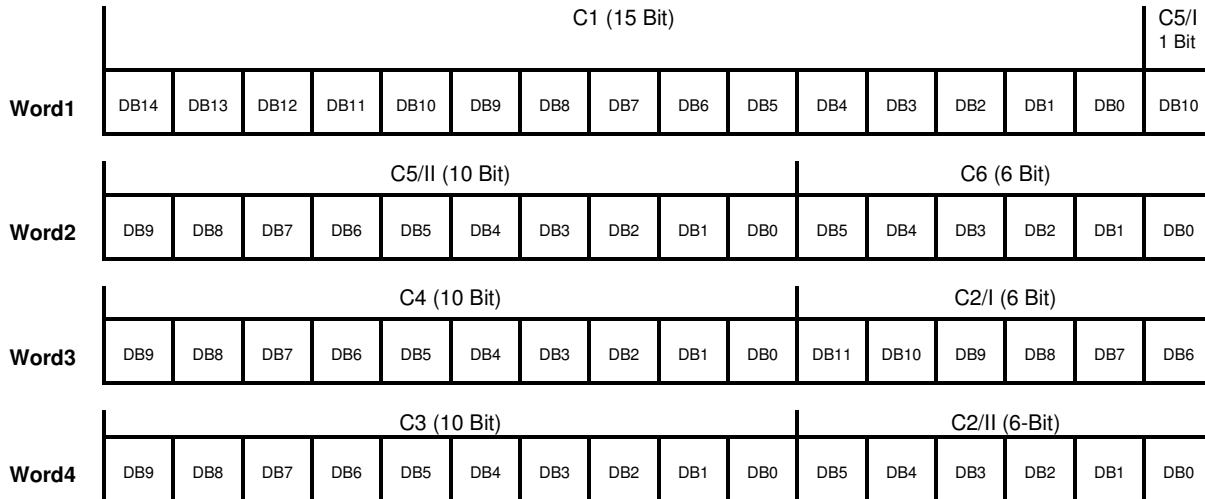


Fig. 4: Arrangement (Bit-pattern) of calibration data in Word1 to Word4

SECOND-ORDER TEMPERATURE COMPENSATION

In order to obtain full temperature accuracy over the whole temperature range, it is recommended to compensate for the non-linearity of the output of the temperature sensor. This can be achieved by correcting the calculated temperature and pressure by a second order correction factor. The second-order factors are calculated as follows:

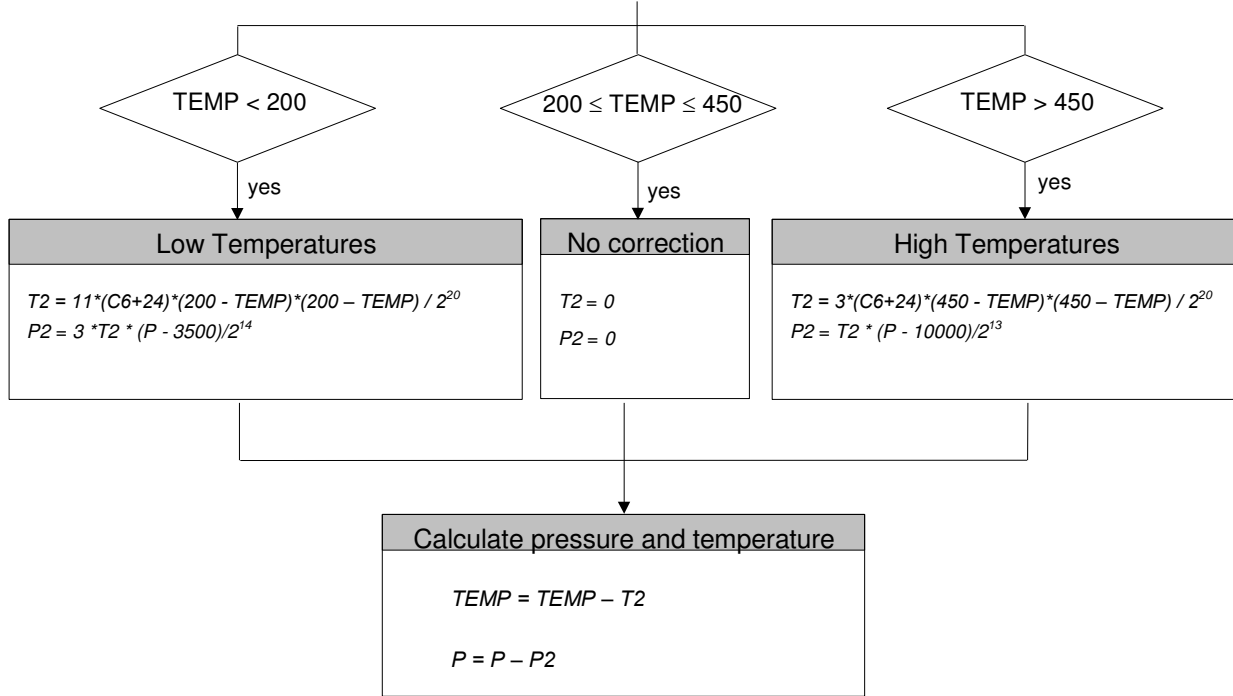


Fig. 5: Flow chart for calculating the temperature and pressure to the optimum accuracy.

SERIAL INTERFACE

The MS5561C communicates with microprocessors and other digital systems via a 3-wire synchronous serial interface as shown in Fig. 1. The SCLK (Serial clock) signal initiates the communication and synchronizes the data transfer with each bit being sampled by the MS5561C on the rising edge of SCLK and each bit being sent by the MS5561C on the rising edge of SCLK. The data should thus be sampled by the microcontroller on the falling edge of SCLK and sent to the MS5561C with the falling edge of SCLK. The SCLK-signal is generated by the microprocessor’s system. The digital data provided by the MS5561C on the DOUT pin is either the conversion result or the software calibration data. In addition, the signal DOUT (Data out) is also used to indicate the conversion status (conversion-ready signal, see below). The selection of the output data is done by sending the corresponding instruction on the pin DIN (Data input).

Following is a list of possible output data instructions:

- Conversion start for pressure measurement and ADC-data-out “D1” (Figure 6a)
- Conversion start for temperature measurement and ADC-data-out “D2” (Figure 6b)
- Calibration data read-out sequence for Word1 (Figure 6c)
- Calibration data read-out sequence for Word2 (Figure 6d)
- Calibration data read-out sequence for Word3 (Figure 6c)
- Calibration data read-out sequence for Word4 (Figure 6d)
- RESET sequence (Figure 6e)

Every communication starts with an instruction sequence at pin DIN. Fig. 6 shows the timing diagrams for the MS5561C. The device does not need a ‘Chip select’ signal. Instead there is a START sequence (3-Bit high) before each SETUP sequence and STOP sequence (3-Bit low) after each SETUP sequence. The SETUP sequence consists in 4-Bit that select a reading of pressure, temperature or calibration data. In case of pressure- (D1) or temperature- (D2) reading the module acknowledges the start of a conversion by a low to high transition at pin DOUT.

Two additional clocks at SCLK are required after the acknowledge signal. Then SCLK is to be held low by the microcontroller until a high to low transition on DOUT indicates the end of the conversion.

This signal can be used to create an interrupt in the microcontroller. The microcontroller may now read out the 16 bit word by giving another 17 clocks on the SLCK pin. It is possible to interrupt the data READOUT sequence with a hold of the SCLK signal. **It is important to always read out the last conversion result before starting a new conversion.**

The RESET sequence is special as the module in any state recognizes its unique pattern. By consequence, it can be used to restart if synchronization between the microcontroller and the MS5561C has been lost. This sequence is 21-bit long. The DOUT signal might change during that sequence (see Fig. 6e). It is recommended to send the RESET sequence before each CONVERSION sequence to avoid hanging up the protocol permanently in case of electrical interference.

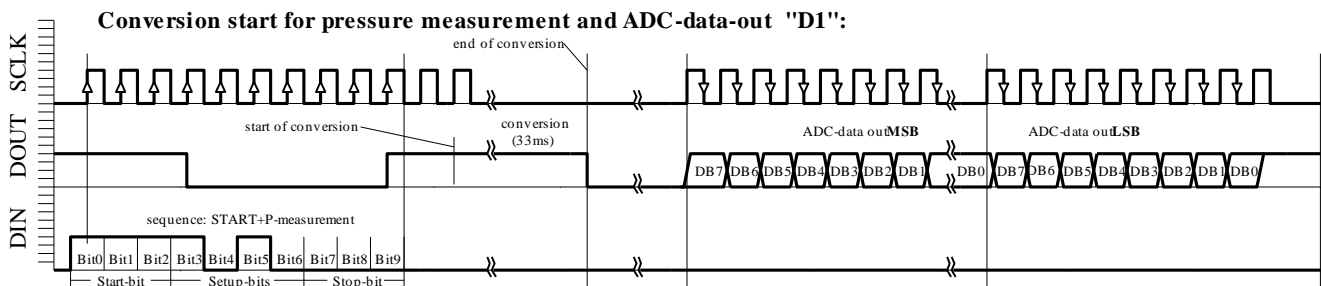


Fig. 6a: D1 ACQUISITION sequence

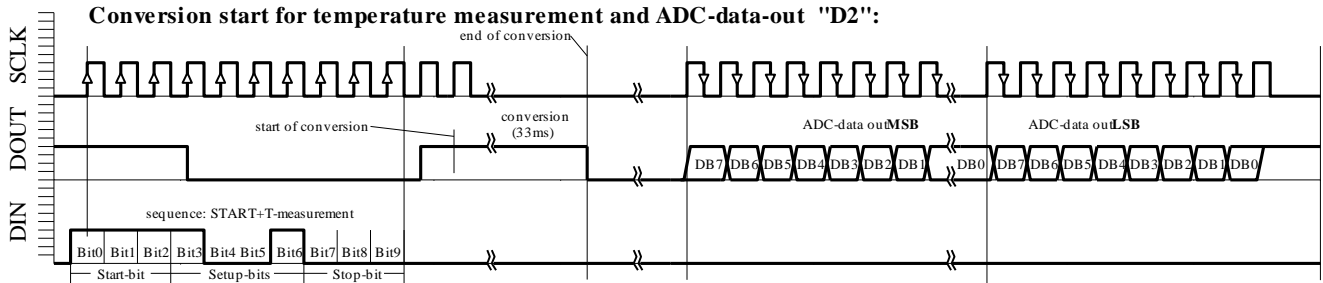


Fig. 6b: D2 ACQUISITION sequence

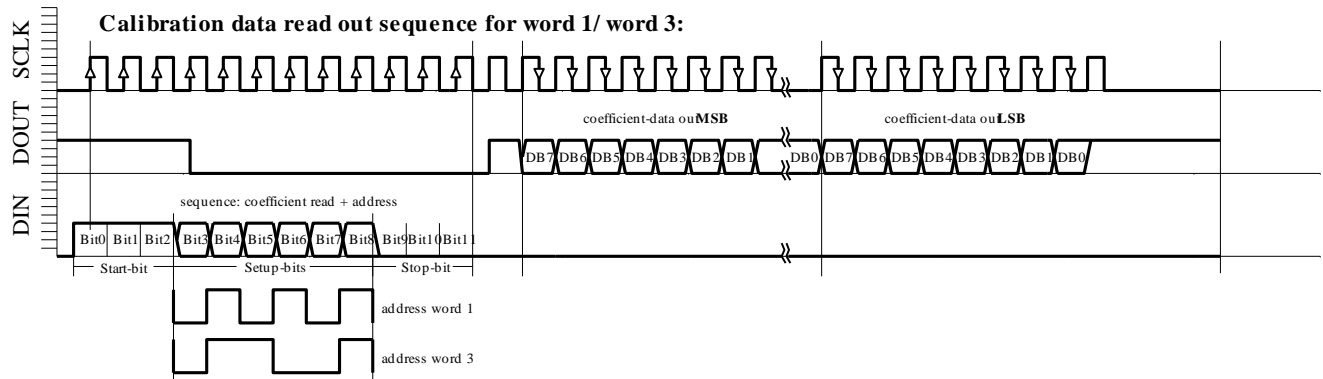


Fig. 6c: Word1, Word3 READING sequence

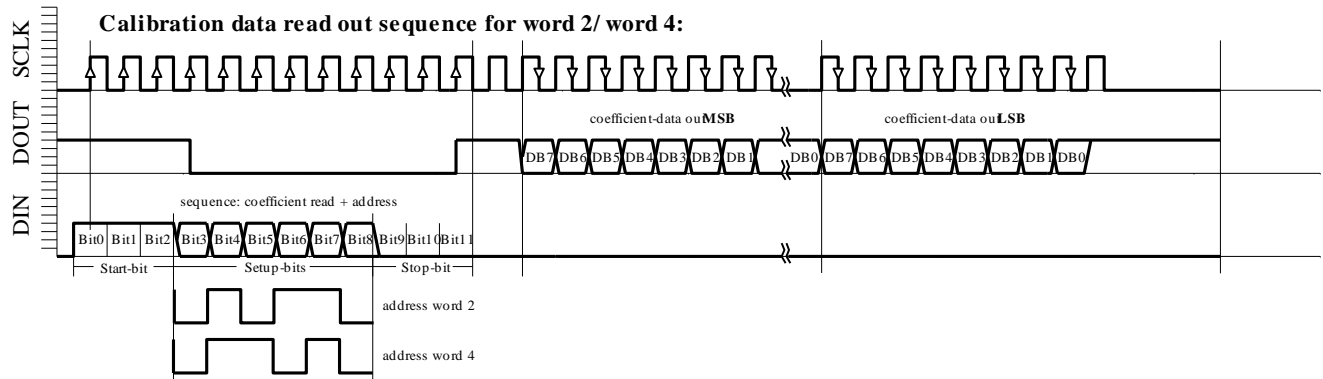


Fig. 6d: W2, W4 READING sequence

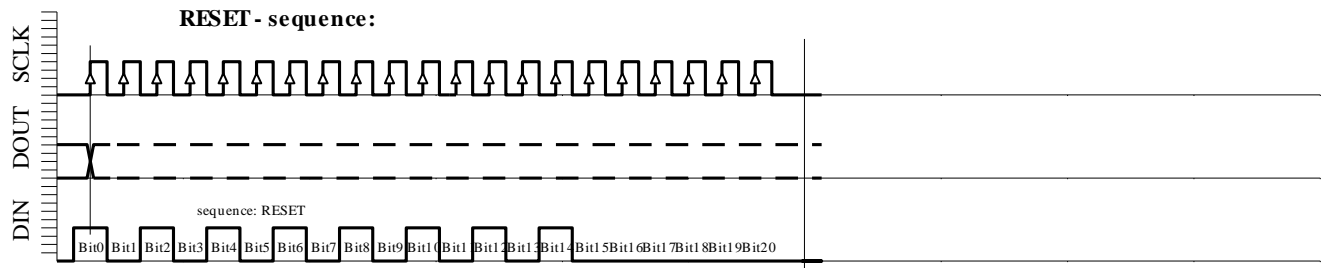


Fig. 6e: RESET sequence (21 bit)

APPLICATION INFORMATION

GENERAL

The advantage of combining a pressure sensor with a directly adapted integrated circuit is to save other external components and to achieve very low power consumption. The main application field for this system includes portable devices with battery supply, but its high accuracy and resolution make it also suited for industrial and automotive applications. The possibility to compensate the sensor by software allows the user to adapt it to his particular application. Communication between the MS5561C and the widely available microcontrollers is realized over an easy-to-use 3-wire serial interface. Customers may select which microcontroller system to be used, and there are no specific standard interface cells required, which may be of interest for specially designed 4 bit-microcontroller applications. For communication via SPI interface please refer to application note AN510 that may be downloaded from the MEAS Switzerland website.

CALIBRATION

The MS5561C is factory calibrated. The calibration data is stored inside the 64 bit PROM memory.

SOLDERING

Please refer to the application note AN808 for all soldering issues.

HUMIDITY, WATER PROTECTION

This module is designed for the integration into portable devices and sufficiently protected against humidity. A silicone gel for enhanced protection against humidity covers the membrane of the pressure transducer. The module must not be used for under water applications.

LIGHT SENSITIVITY

The MS5561C is protected against sunlight by a layer of white gel. It is, however, important to note that the sensor may still be slightly sensitive to sunlight, especially to infrared light sources. This is due to the strong photo effect of silicon. As the effect is reversible there will be no damage, but the user has to take care that in the final product the sensor cannot be exposed to direct light during operation.

DECOUPLING CAPACITOR

Particular care must be taken when connecting the device to power supply. A 47 μ F tantalum capacitor **must** be placed as close as possible of the MS5561C's VDD pin. This capacitor will stabilize the power supply during data conversion and thus, provide the highest possible accuracy.

APPLICATION EXAMPLE: ALTIMETER SYSTEM USING MS5561C

MS5561C is a circuit that can be used in connection with a microcontroller in mobile altimeter applications. It is designed for low-voltage systems with a supply voltage of 3V, particularly in battery applications. The MS5561C is optimised for low current consumption as the AD-converter clock (MCLK) can use the 32.768 kHz frequency of a standard watch crystal, which is supplied in most portable watch systems.

For applications in altimeter systems MEAS Switzerland can deliver a simple formula to calculate the altitude, based on a linear interpolation, where the number of interpolation points influences the accuracy of the formula.

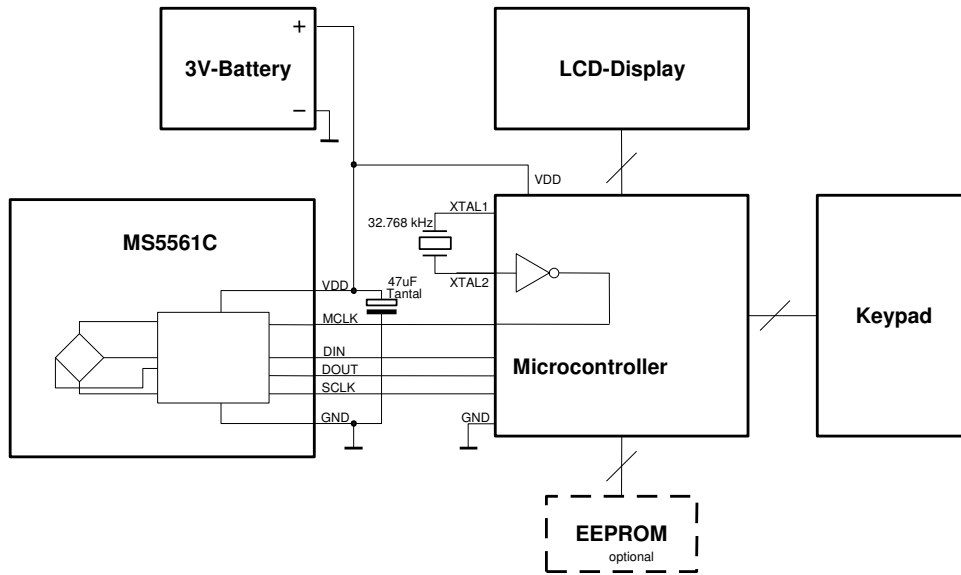
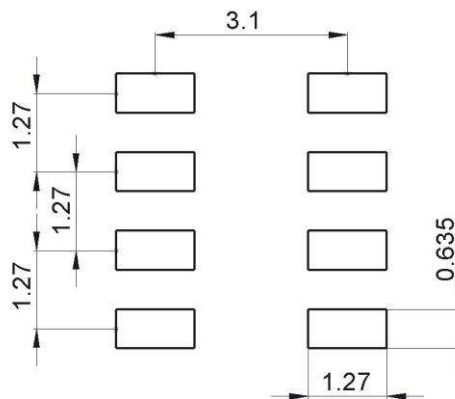


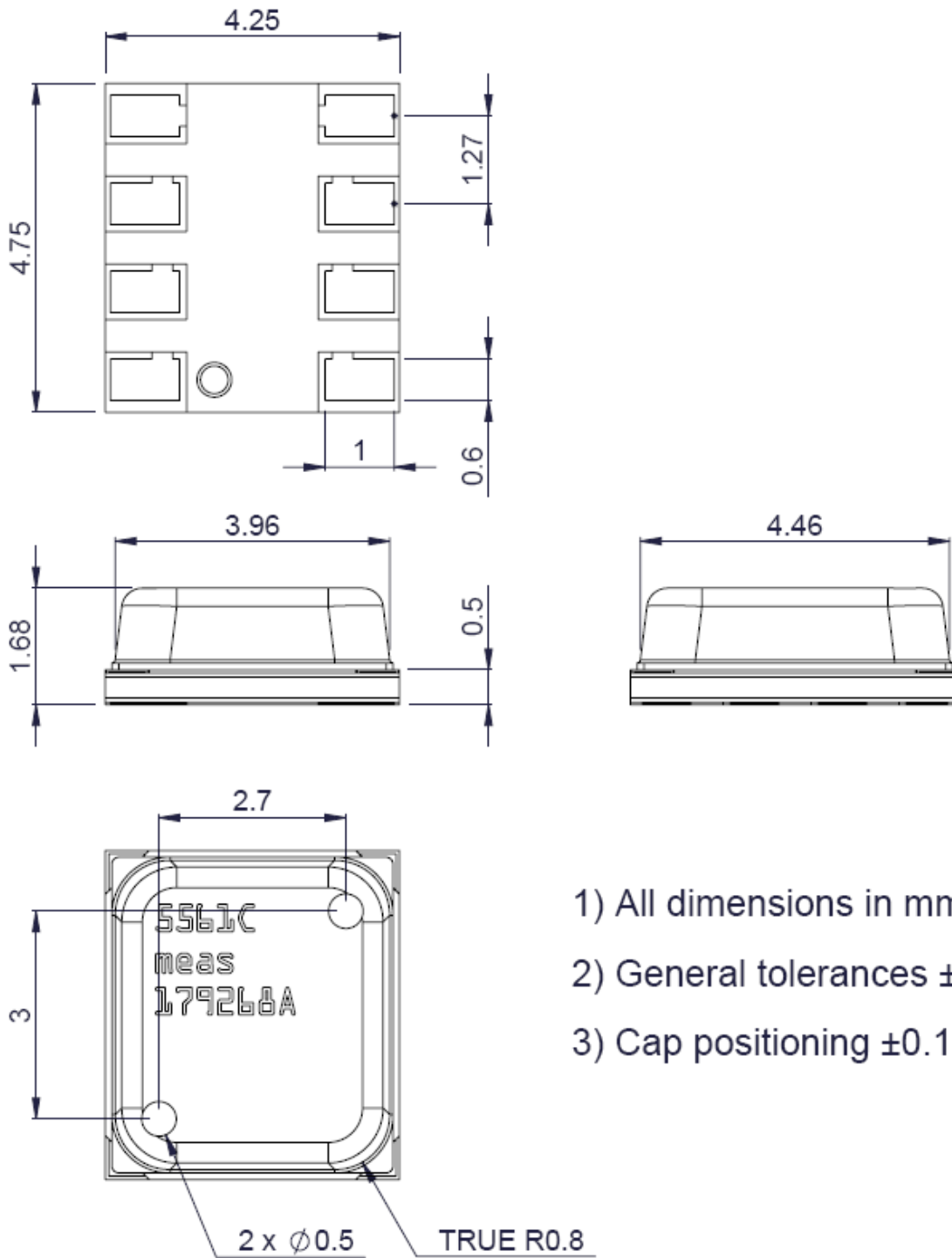
Figure 7: Demonstration of MS5561C in a mobile altimeter

RECOMMENDED PAD LAYOUT

Pad layout for bottom side of MS5561C soldered onto printed circuit board.



DEVICE PACKAGE OUTLINES



- 1) All dimensions in mm
- 2) General tolerances ± 0.1
- 3) Cap positioning ± 0.1

Fig. 8: Device package outlines of **MS5561-C**

ASSEMBLY

MOUNTING

The MS5561C can be placed with automatic Pick&Place equipment using vacuum nozzles. It will not be damaged by the vacuum. Due to the low stress assembly the sensor does not show pressure hysteresis effects.

It is important to solder all contact pads to avoid floating of the sensor during soldering. The pins PEN and PV shall be left open or connected to VDD. Do not connect the pins PEN and PV to GND!

CLEANING

The MS5561C has been manufactured under cleanroom conditions. Each device has been inspected for the homogeneity and the cleanness of the silicone gel. It is therefore recommended to assemble the sensor under class 10'000 or better conditions. Should this not be possible, it is recommended to protect the sensor opening during assembly from entering particles and dust. To avoid cleaning of the PCB, solder paste of type "no-clean" shall be used. **Cleaning might damage the sensor!**

ESD PRECAUTIONS

The electrical contacts except programming pads are protected against ESD up to 4 kV HBM (human body model). The MS5561C is shipped in antistatic transport boxes. Any test adapters or production transport boxes used during the assembly of the sensor shall be of an equivalent antistatic material.

SHIPPING PACKAGE

Tape

Units per reel	4'000	Minimum empty leader (right side of drawing)	250 mm
Tape widths	12 mm	Minimum empty trailer (left side of drawing, direction of unreeling)	250 mm
Tape material	Black Conductive Polystyrene		
Reel diameter	13" / 330 mm		

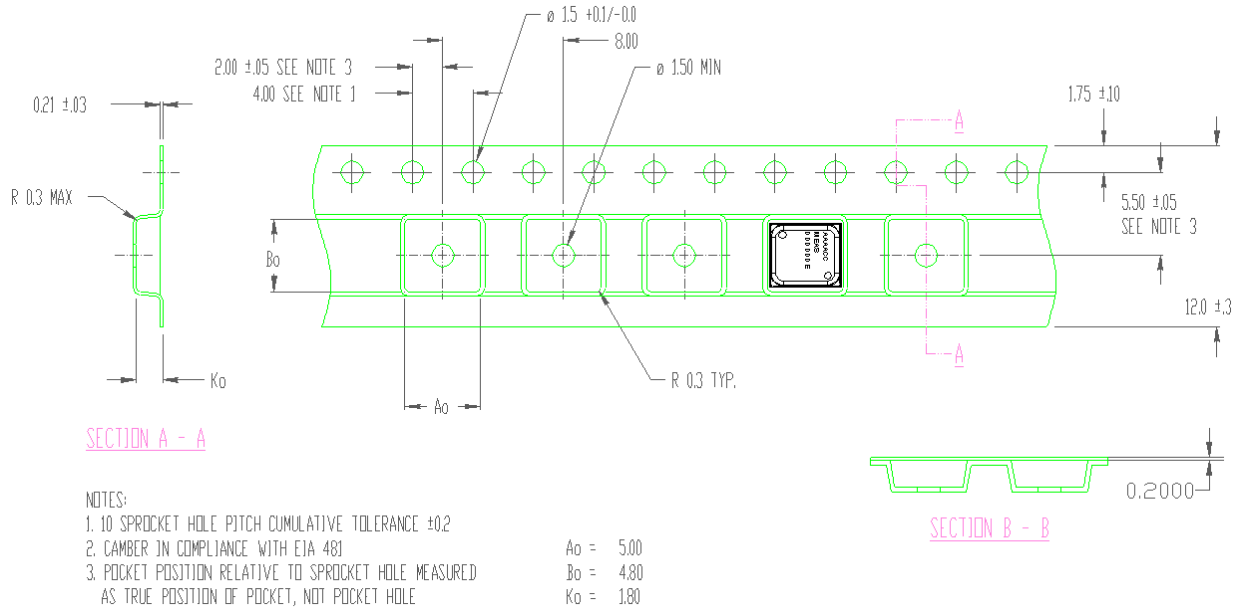


Fig. 9: Outline of tape for MS5561C

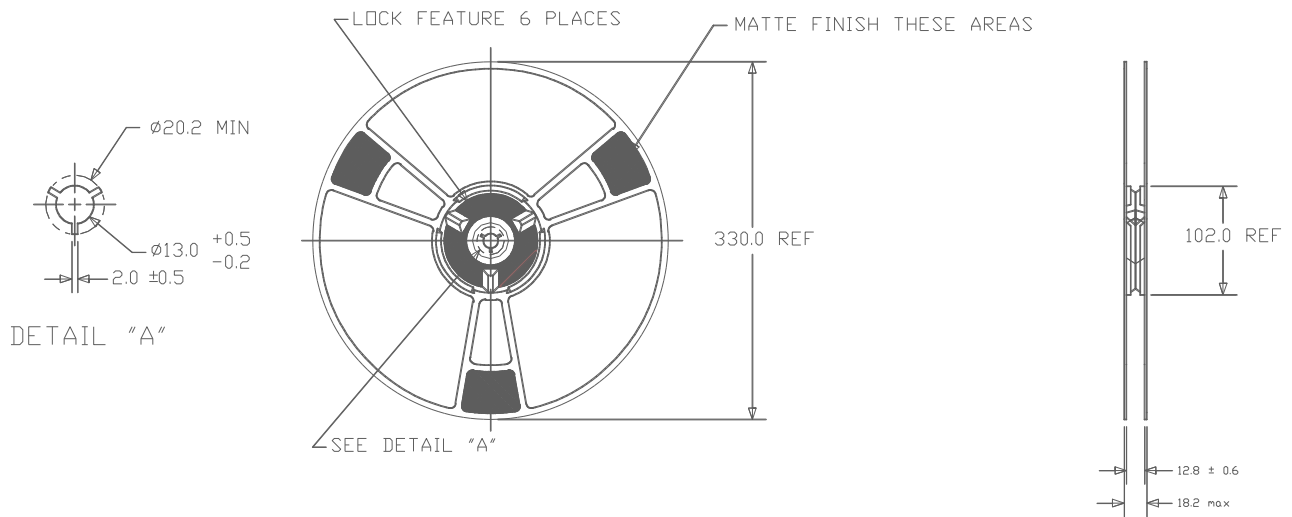


Fig.10: Outline of reel for MS5561C

MS5561C

Micro Altimeter

ORDERING INFORMATION

Product Code	Product	Art. No	Package	Comments
MS5561-C	Micro Altimeter	325561000	Small Size SMD with metal lid	Module height 1.6 mm

NORTH AMERICA

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Fax: +1 510 498 1578
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Website: www.meas-spec.com

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